

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|------------------|---------|------------------|
| L1 | 707 | 257/100.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 12:50 |
| L2 | 2137 | 257/99.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 13:15 |
| L3 | 1826 | 2 not 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 12:51 |
| L4 | 1021 | (led or (light adj emitter) or illuminator) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/11 12:51 |
| L5 | 1789 | 3 not L4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 12:52 |
| L6 | 846 | 257/88.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 13:16 |
| L7 | 832 | 6 not 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 13:16 |
| L8 | 681 | 7 not 2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 13:16 |

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| L9 | 666 | 8 not 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 13:16 |
| S6 | 1 | ("5479029").PN. | USPAT | OR | OFF | 2004/11/16 16:16 |
| S7 | 449 | (led or (light adj emitter)) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin) and (wires or wire) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 00:24 |
| S8 | 317 | S7 and (gold or silver or au or ag) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 16:19 |
| S9 | 212 | S8 and (nickel or titanium or ti or ni) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 17:52 |
| S10 | 1 | "5917234".PN. | USPAT; USOCR | OR | OFF | 2004/11/16 17:46 |
| S11 | 1 | "5893724".PN. | USPAT; USOCR | OR | OFF | 2004/11/16 17:47 |
| S12 | 1 | "5773895".PN. | USPAT; USOCR | OR | OFF | 2004/11/16 17:47 |
| S13 | 1 | "5767446".PN. | USPAT; USOCR | OR | OFF | 2004/11/16 17:47 |
| S14 | 741 | 257/88.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:12 |
| S15 | 1112 | 257/79.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:12 |
| S16 | 564 | 257/81.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:13 |

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| S17 | 335 | 257/95.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:13 |
| S18 | 1877 | 257/99.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:13 |
| S19 | 576 | 257/100.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:13 |
| S20 | 4328 | S14 S15 S16 S17 S18 S19 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 18:13 |
| S21 | 262 | S20 and (heat adj sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S22 | 768831 | "15" and (resin or epoxy or encapsulant) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:02 |
| S23 | 1112 | 257/79.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:02 |
| S24 | 294 | S23 and (resin or epoxy or encapsulant) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |

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| S25 | 741 | 257/88.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S26 | 564 | 257/81.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S27 | 335 | 257/95.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S28 | 1877 | 257/99.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S29 | 576 | 257/100.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 12:43 |
| S30 | 4328 | S25 S23 S26 S27 S28 S29 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S31 | 1517 | S30 and (resin or epoxy or encapsulant) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |
| S32 | 262 | S30 and (heat adj sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:03 |

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| S33 | 1399 | S31 not S32 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/16 20:04 |
| S34 | 7487 | (led or (light adj (emitter or emitting))) and (heat adj sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 15:55 |
| S35 | 339 | S34 and ((bond or bonding) adj pads) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 15:56 |
| S36 | 132 | S35 and (semiconductor near5 substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:51 |
| S37 | 1538 | 362/800.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:52 |
| S38 | 803 | 362/240.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:52 |
| S39 | 1822 | 362/294.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:52 |
| S40 | 752 | 362/373.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:52 |

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| S41 | 4250 | S37 S38 S39 S40 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/18 19:52 |
| S42 | 73 | S41 and ((semiconductor or si or silicon) near6 substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |
| S43 | 964 | 372/36.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/19 12:50 |
| S44 | 964 | 372/36.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:26 |
| S45 | 1018 | (led or (light adj emitter) or illuminator) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/11 00:27 |
| S46 | 770 | S45 and (wire or wires) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/11 00:26 |
| S47 | 846 | 257/88.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S48 | 1379 | 257/79.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |

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| S49 | 665 | 257/81.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S50 | 367 | 257/95.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S51 | 2137 | 257/99.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S52 | 707 | 257/100.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S53 | 5016 | S47 S48 S49 S50 S51 S52 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S54 | 336 | S53 and (heat adj sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:18 |
| S55 | 1695 | 362/800.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |
| S56 | 855 | 362/240.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |

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| S57 | 1910 | 362/294.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |
| S58 | 813 | 362/373.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |
| S59 | 4525 | S55 S56 S57 S58 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:23 |
| S60 | 86 | S59 and ((semiconductor or si or silicon) near6 substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:24 |
| S61 | 1066 | 372/36.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/11 09:26 |